



ABSTRACT

5 A resin sealing type semiconductor device includes an internal heat radiator having an element placing surface, a semiconductor element bonded to the element placing surface and leads which are separated from the semiconductor element. Wires electrically connect the leads to the electrodes of the semiconductor element. An insulator is located between the internal heat radiator and the leads. A resin package is formed exposing an exposed area of the internal heat radiator.

10 A heat radiating fin is bonded to the exposed area of the internal heat radiator by a solder layer therebetween. The dimension S1 of the exposed area is equal to or larger than the dimension S2 of the bonding area of the heat radiating fin and the solder layer.